# Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904) Contact Info: ti.com/support Form/Declaration Type: Distribute - RoHS and IEC 62474 DB Created on: 05/30/2022

Details for "INA592IDRCT"

# **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
INA592IDRCT	NIPDAU	Level-2-260C-1 YEAR	TI Semiconductor	DRC   10	3x3x0.9	29.7

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

### **Environmental Ratings Information**

Yes Yes Yes Yes	RoHS	REACH	Green	IEC 62474 DB
165 165 165	Yes	Yes	Yes	Yes

## **Component Information**

			Homogeneous Material Level		Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.01638	97.534834	975348	0.055105	551
Not Categorized	Proprietary Materials		0.000002	0.011909	119	0.000007	0
Precious Metals	Gold	7440-57-5	0.000009	0.053591	536	0.00003	0
Precious Metals	Palladium	7440-05-3	0.000403	2.399667	23997	0.001356	14
Sub-Total			0.016794	100	1000000	0.056498	565
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.572545	80.000028	800000	1.926141	19261
Thermoplastics	Epoxy	85954-11-6	0.143136	19.999972	200000	0.481535	4815
Sub-Total			0.715681	100	1000000	2.407676	24077
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	15.6032	97.52	975200	52.491891	524919
Copper and Its Alloys	Iron	7439-89-6	0.368	2.3	23000	1.238016	12380
Copper and Its Alloys	Phosphorus	7723-14-0	0.0048	0.03	300	0.016148	161
Zinc and Its Alloys	Zinc	7440-66-6	0.024	0.15	1500	0.08074	807
Sub-Total			16	100	1000000	53.826796	538268
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.466088	95.12	951200	1.568001	15680
Precious Metals	Gold	7440-57-5	0.003822	0.78	7800	0.012858	129
Precious Metals	Palladium	7440-05-3	0.02009	4.1	41000	0.067586	676
Sub-Total			0.49	100	1000000	1.648446	16484
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	9.044017	88	880000	30.425654	304257
Other Organic Materials	Chlorine	7782-50-5	0.000103	0.001002	10	0.000347	3
Other Plastics and Rubber	Carbon Black	1333-86-4	0.030832	0.300001	3000	0.103724	1037
Thermoplastics	Epoxy	85954-11-6	1.20234	11.698996	116990	4.044882	40449
Sub-Total			10.277292	100	1000000	34.574606	345746
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.225205	100	1000000	7.485978	74860
Sub-Total			2.225205	100	1000000	7.485978	74860
Total			29.724972	1		100	1000000

#### Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

### Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

#### Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

## Material Declaration Certificate for Semiconductor IC Packaged Products

T certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

#### Important Information/Disclaimer

To bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

## Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/30/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Po+Free." These TI semiconductor are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.